

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled).
2. (Currently Amended) The method of manufacturing a semiconductor device as defined in claim ~~48~~19,

wherein the interconnecting lines comprise connecting portions electrically connecting with the bumps, and

wherein in the step of ~~electrical connection~~mounting the first semiconductor chips, the base substrate is melted, so that connections of the bumps and the connecting portions are sealed with the melted material of the base substrate.

3. (Currently Amended) The method of manufacturing a semiconductor device as defined in claim ~~48~~19,

wherein the melted material of the base substrate is adhered closely to a surface of the first semiconductor chip.

4. (Canceled).
5. (Currently Amended) The method of manufacturing a semiconductor device as defined in claim ~~48~~19,

wherein a thermoplastic resin is used as the base substrate.

6. (Canceled).
7. (Canceled)
8. (Currently Amended) A semiconductor device manufactured by the manufacturing method as defined in claim ~~48~~19.

- 9.-18. (Canceled)

19. (New) A method of manufacturing a semiconductor device, the method comprising:

mounting a first semiconductor chip on a first surface of a base substrate so that bumps on the first semiconductor chip are in contact with the first surface of the base substrate, then heating at least the bumps and pressing the first semiconductor chip toward the base substrate so that the base substrate is melted and the bumps are pushed into the base substrate from the first surface through the base substrate to a second surface opposite to the first surface, and then electrically connecting the bumps to interconnecting lines formed on the second surface of the base substrate; and

mounting a second semiconductor chip on the second surface of the base substrate so that the second semiconductor chip is electrically connected to the interconnecting lines.

20. (New) The method of manufacturing a semiconductor device as defined in claim 19, further comprising:

providing an adhesive material between the second semiconductor chip and the base substrate.

21. (New) The method of manufacturing a semiconductor device as defined in claim 19,

wherein the first and second semiconductor chips are mounted nearly at the same time.